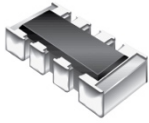


MATERIAL DECLARATION SHEET



Material Number	CAY10A-x2AS			
Product Line	Chip Resistor Array			
Compliance Date	2019/09/06			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CAS if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.000818897	Aluminum oxide	1344-28-1	96%	76.05%	79.22%
				Magnesium oxide	14808-82-7	3%	2.38%	
				Silicon dioxide	1309-48-4	1%	0.79%	
2	Conductor Layer	Conductor Layer	0.000039074	Silver	7440-22-4	86%	3.56%	3.78%
				Palladium	7440-05-3	1%	0.03%	
				Glass	65997-17-3	13%	0.19%	
3	Resistive Element	Resistive Element	0.000025946	Ruthenium (IV) oxide	12036-10-1	25%	0.3%	2.01%
				Silver	7440-22-4	33.33%	1.21%	
				Lead-containing glass	7439-92-1	25%	0.3%	
				Palladium	7440-5-3	16.67%	0.20%	
4	Over-Coating	Epoxy	0.000024705	Talc	14807-96-6	20%	0.578%	2.89%
				Silicon dioxide	60676-86-0	30%	0.867%	
				Epoxy	25068-38-6	50%	1.445%	
5	End Terminal	Metal	0.000037007	Silver	7440-22-4	83%	2.97%	3.58%
				Epoxy resin	25085-99-8	17%	0.61%	
6	Ni Plating	Nickel	0.000048377	Nickel	7440-02-0	100%	4.68%	4.68%
7	Sn Plating	Tin	0.000039694	Tin	7440-31-5	100%	3.84%	3.84%
		Total weight	0.0010337					

MATERIAL DECLARATION SHEET



This Document was updated on: 2019/09/06

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I